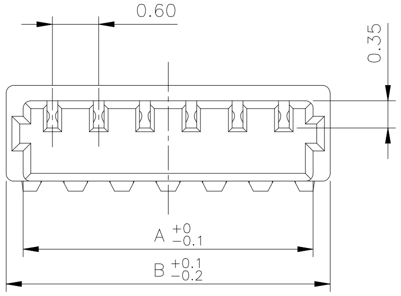
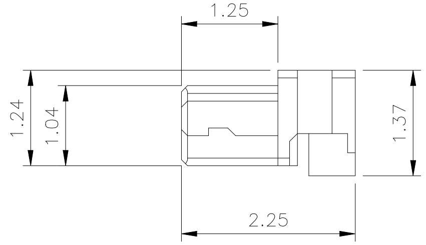
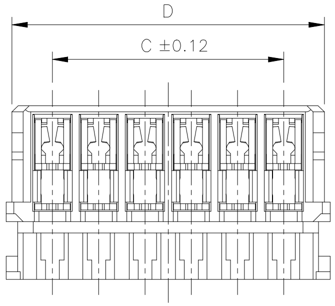
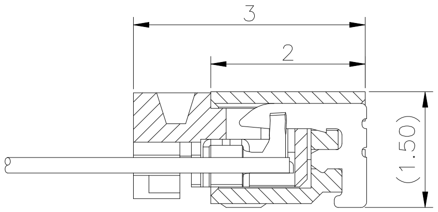
REV.	ECN NO.	REVISIONS	REV.DRAWN	DATE
A		初版发行	Asimo	2009/07/30
B		修正LOGO、穴号位置	sunquan	2013/05/06
C		修正图面	sunquan	2016/01/20
D		修正图面	YangSong	2016/04/11



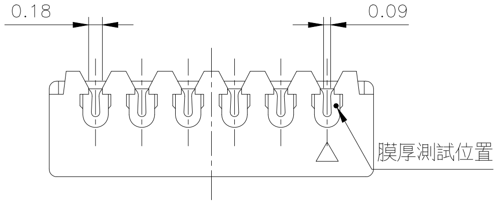


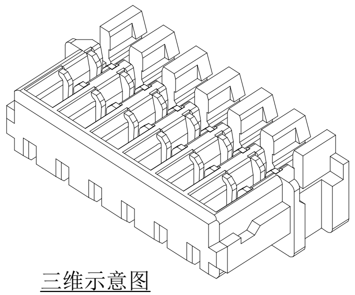
NOTES:
1.HOUSING:HEAT RESISTANT RESIN,UL94V−0
2.CONTACT:COPPER ALLOY,T=0.08
3.MATE WITH:JS−ID0601X−XX SERIES
4.APPLICABLE WIRE: CONDUCTOR SIZE:AWG #34、AWG#36
5.PART NO.
JS−ID0600−XXXX−XX
POLES:2~30
BLANK:NORMAL
NH:HALOGEN FREE
BLANK:TIN PLATED
M:MATTE TIN
G0:GOLD PLATED
6.HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON THE PACKING



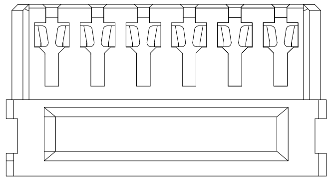


MATED CONDITION





三维示意图



CIRCUITS	DIMENSION			
	A	B	C	D
2	1.36	1.80	0.60	1.65
4	2.56	3.00	1.80	2.85
5	3.16	3.60	2.40	3.45
6	3.76	4.20	3.00	4.05
8	4.96	5.40	4.20	5.25
10	6.16	6.60	5.40	6.45
12	7.36	7.80	6.60	7.65
16	9.76	10.20	9.00	10.05

X. ± 0.50	X.° ± 5.0°
.X ± 0.20	.X° ± 2.0°
.XX ± 0.10	.XX° ± 1.0°
.XXX± 0.05	.XXX°± 0.5°

符 合 环 境 管 理 物 质

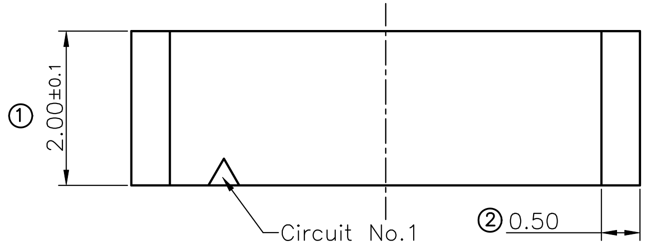
UNITS: mm
MATERIAL: SEE NOTE
FINISH: SEE NOTE
Q'TY: SEE NOTE

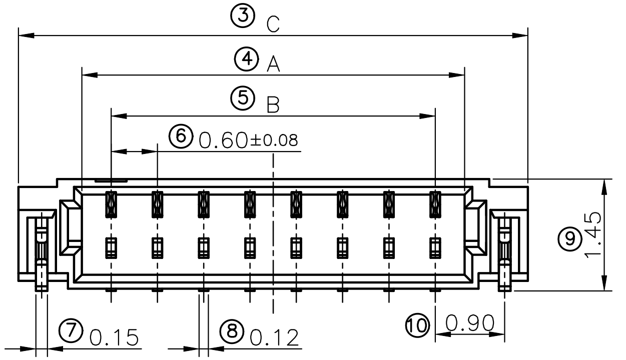
NAME(INTENDED USE): CUSTOMER
PART NO.(INTENDED USE): JS−ID0600−XX
APPD:
CHKD:
DR: Asimo 2009/07/30

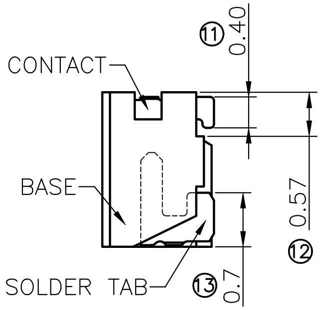
CHYAO SHIUNN ELECTRONIC (SHANGHAI) CO.,LTD.
TITLE: 0.6mm Pitch Wire to Board Conn.
DWG NO.: 010−0064−0600−XX

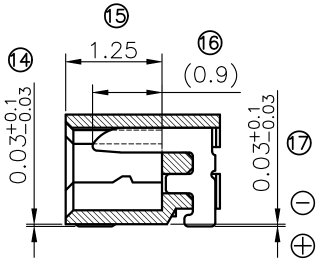
SCALE	SHEET	REV.
10:1	1/1	/

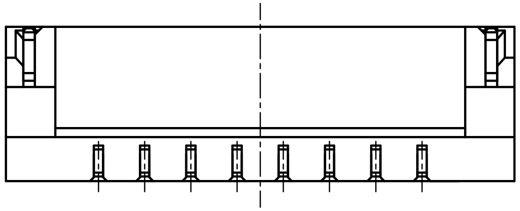
REV.	ECN NO.	REVISIONS	REV.DRAWN	DATE
B	╱	增加镀金规格	Asimo	2009/11/17
C	╱	增加无卤识别码	Asimo	2010/03/30
D	╱	增加雾锡规格	sunquan	2010/11/15
E	╱	增加电镀膜厚标示	sunquan	2011/07/25
F	╱	增加反向出料规格	sunquan	2012/11/05

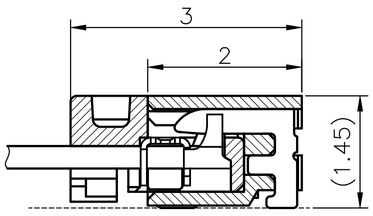




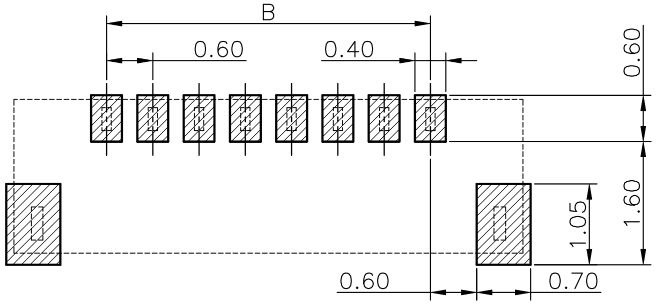








Assembly Layout



RECOMMENDED P.C.B LAYOUT(TOP VIEW)

GENERAL TOLERANCE: ±0.05

NOTES:
1.BASE:HEAT RESISTANT RESIN,UL94V−0
2.CONTACT:PHOSPHOR BRONZE,T=0.12mm
3.SOLDER TAB:BRASS,T=0.15mm
4.MATE WITH:JS−ID0600−XX SERIES
5.PART NO.
JS−ID0601H−XXXX−XXX
POLES:2~30
BLANK:TIN PLATED
Sn>100μ",Ni>30μ"
M:MATTE SN
Sn>100μ",Ni>30μ"
GO:GOLD PLATED
Cotact:Au>0.8μ",Ni>30μ"
Nail:Sn>100μ",Ni>30μ"
B: BACKWARD FEED
BLANK: FORWARD FEED
BLANK:NORMAL
NH:HALOGEN FREE
6.HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON THE PACKING

POLES	A	B	C	POLES	A	B	C
				16	9.76	9.00	11.40
02	1.36	0.60	3.00	17	10.36	9.60	12.00
03	1.96	1.20	3.60	18	10.96	10.20	12.60
04	2.56	1.80	4.20	19	11.56	10.80	13.20
05	3.16	2.40	4.80	20	12.16	11.40	13.80
06	3.76	3.00	5.40	21	12.76	12.00	14.40
07	4.36	3.60	6.00	22	13.36	12.60	15.00
08	4.96	4.20	6.60	23	13.96	13.20	15.60
09	5.56	4.80	7.20	24	14.56	13.80	16.20
10	6.16	5.40	7.80	25	15.16	14.40	16.80
11	6.76	6.00	8.40	26	15.76	15.00	17.40
12	7.36	6.60	9.00	27	16.36	15.60	18.00
13	7.96	7.20	9.60	28	16.96	16.20	18.60
14	8.56	7.80	10.20	29	17.56	16.80	19.20
15	9.16	8.40	10.80	30	18.16	17.40	19.80

X. ± 0.50	X.° ± 5.0°
.X ± 0.20	.X° ± 2.0°
.XX ± 0.10	.XX° ± 1.0°
.XXX± 0.05	.XXX°± 0.5°

UNITS: mm
MATERIAL: SEE NOTE
FINISH: SEE NOTE
Q'TY: SEE NOTE

NAME(INTENDED USE): Wafer(CUSTOMER)
PART NO.(INTENDED USE): JS−ID0601H−XX
APPD: liuzhiwen 2011/07/25
CHKD:
DR: Asimo 2010/03/30

CHYAO SHIUNN ELECTRONIC (SHANGHAI) CO.,LTD.

TITLE: 0.6mm Pitch Wire to Board Conn. Wafer

DWG NO.: 010−0064−0601H−XX

SCALE	SHEET	REV.
10:1	1/1	/

符合环境管理物质